PHOTON IS OUR BUSINESS



Photodiode arrays with amplifiers

S11865-64/-128/-256 S11866-64-02/-128-02

Photodiode arrays combined with signal processing IC

The S11865/S11866 series are Si photodiode arrays combined with a signal processing IC chip. X-ray tolerance has been improved compared to the previous products (S8865/S8866 series). The signal processing IC chip is formed by CMOS process and incorporates a timing generator, shift register, charge amplifier array, clamp circuit and hold circuit, making the external circuit configuration simple. A long, narrow image sensor can also be configured by arranging multiple arrays in a row. For X-ray detection applications, types with phosphor sheet affixed on the photosensitive area are also available.

As the dedicated driver circuit, the C9118-01 (sold separately) is provided (this circuit does not support the S11865-256).

Features

- → Data rate: 1 MHz max.
- Element pitch: 5 types available \$11865-64: 0.8 mm pitch × 64 ch \$11865-128: 0.4 mm pitch × 128 ch \$11865-256: 0.2 mm pitch × 256 ch \$11866-64-02: 1.6 mm pitch × 64 ch \$11866-128-02: 0.8 mm pitch × 128 ch
- 5 V power supply operation
- Simultaneous integration by using a charge amplifier array
- Sequential readout with a shift register
- Low dark current due to zero-bias photodiode operation
- **➡** Integrated clamp circuit allows low noise and wide dynamic range
- Integrated timing generator allows operation at two different pulse timings
- Types with phosphor sheet affixed on the photosensitive area are available for X-ray detection (S11865-64G/-128G/-256G, S11866-64G-02/-128G-02)

- Applications

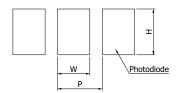
- **■** Long and narrow line sensors
- **■** Line sensors for X-ray detection

Structure

Parameter	Symbol*1	S11865-64	S11865-128	S11865-256	S11866-64-02	S11866-128-02	Unit
Element pitch	Р	0.8	0.4	0.2	1.6	0.8	mm
Element width	W	0.7	0.3	0.1	1.5	0.7	mm
Element height	Н	0.8	0.6	0.3	1.6	0.8	mm
Number of elements	-	64	128	256	64	128	-
Effective photosensitive area length	-	51.2	51.2	51.2	102.4	102.4	mm
Board material	-			Glass epoxy			_

^{*1:} Refer to following figure.

Enlarged drawing of photosensitive area



KMPDC0072EA

♣ Absolute maximum ratings (Ta=25 °C, unless otherwise noted)

Parameter	Symbol	Value	Unit
Supply voltage	Vdd	-0.3 to +6	V
Reference voltage	Vref	-0.3 to +6	V
Photodiode voltage	Vpd	-0.3 to +6	V
Gain selection terminal voltage	Vgain	-0.3 to +6	V
Master/slave selection voltage	Vms	-0.3 to +6	V
Clock pulse voltage	V(CLK)	-0.3 to +6	V
Reset pulse voltage	V(RESET)	-0.3 to +6	V
External start pulse voltage	V(EXTSP)	-0.3 to +6	V
Operating temperature*2	Topr	-5 to +60	°C
Storage temperature*2	Tstg	-10 to +70	°C

^{*2:} No dew condensation

When there is a temperature difference between a product and the surrounding area in high humidity environment, dew condensation may occur on the product surface. Dew condensation on the product may cause deterioration in characteristics and reliability.

Note: Exceeding the absolute maximum ratings even momentarily may cause a drop in product quality. Always be sure to use the product within the absolute maximum ratings.

■ Recommended terminal voltage (Ta=25 °C)

Parameter		Symbol	Min.	Тур.	Max.	Unit
Supply voltage		Vdd	4.75	5	5.25	V
Reference voltage		Vref	4	4.5	4.6	V
Photodiode voltage		Vpd	-	Vref	-	V
Gain selection terminal voltage	High gain	Vgain	Vdd - 0.25	Vdd	Vdd + 0.25	V
dani selection terminal voltage	Low gain	vyaiii	0	-	0.4	V
Mactor/clave colection voltage	High level*3	Vms	Vdd - 0.25	Vdd	Vdd + 0.25	V
Master/slave selection voltage	Low level*4	VIIIS	0	-	0.4	V
Clock pulse voltage	High level	V(CLK)	3.3	Vdd	Vdd + 0.25	V
Clock pulse voltage	Low level	V(CLK)	0	-	0.4	V
Reset pulse voltage	High level	WDECET)	3.3	Vdd	Vdd + 0.25	V
Reset puise voitage	Low level	V(RESET)	0	-	0.4	V
External start pulse voltage	High level	V(EXTSP)	Vdd - 0.25	Vdd	Vdd + 0.25	V
External start pulse voltage	Low level	V(EXTSP)	0	-	0.4	V

^{*3:} Parallel

■ Electrical characteristics [Ta=25 °C, Vdd=5 V, V(CLK)=V(RESET)=5 V]

Pai	rameter	Symbol	Min.	Тур.	Max.	Unit
Clock pulse frequency*	5	f(CLK)	40	-	4000	kHz
	S11865-64, S11866-64-02		-	-	14678	
Line rate*6	S11865-128, S11866-128-02	LR	-	-	7568	lines/s
	S11865-256		-	-	3844	
Output impedance	Output impedance		-	3	-	kΩ
	S11865-64, S11866-64-02		-	16	-	
Current consumption	S11865-128, S11866-128-02	Ic	-	30	-	mA
	S11865-256		-	60	-	
Charge amp feedback capacitance High gain Low gain		Cf	-	0.5	-	nE
		Cf	-	1	-	pF

^{*5:} Video data rate is 1/4 of clock pulse frequency f(CLK).



^{*4:} Serial at 2nd or later stages

^{*6:} The values depend on the clock pulse frequency.

= Electrical and optical characteristics [Ta=25 °C, Vdd=5 V, V(CLK)=V(RESET)=5 V, Vgain=5 V (High gain), 0 V (Low gain)]

S11865-64/-128/-256

Parameter		Cumbal	S11865-64 S11865		11865-12	-128 S11865-256		56	Linit			
Paramete	: 1	Symbol	Min.	Тур.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Unit
Spectral response range		λ	20	0 to 100	0	20	00 to 100	0	20	00 to 100	00	nm
Peak sensitivity wavelen	gth	λр	-	720	-	-	720	-	-	720	-	nm
Dark output voltage*7	High gain	Vd	-	0.01	0.2	-	0.01	0.2	-	0.01	0.2	m\/
Dark output voitage	Low gain	vu	-	0.005	0.1	-	0.005	0.1	-	0.005	0.1	mV
Saturation output voltag	е	Vsat	3.0	3.5	-	3.0	3.5	-	3.0	3.5	-	V
Saturation exposure*8	High gain	Foot	-	0.8	1.0	-	2.4	3.0	-	15	19	mlus
Saturation exposure •	Low gain	Esat	-	1.6	2.0	-	4.8	6.0	-	30	37.5	mlx · s
Dhotoconcitivity	High gain	Sw	3520	4400	-	1200	1500	-	200	250	-	V//
Photosensitivity	Low gain	3W	1760	2200	-	600	750	-	100	125	-	V/ <i>lx</i> · s
Photoresponse nonuniformity*9		PRNU	-	-	±10	-	-	±10	-	-	±10	%
NI-!+10	High gain	N	-	1.3	2.0	-	1.0	1.5	-	0.8	1.2	m\/ rmc
Noise*10	Low gain	N	-	0.7	1.1	-	0.6	0.9	-	0.5	0.75	mV rms
Output offset voltage*11		Voffset	-	Vref	-	-	Vref	-	-	Vref	-	V

S11866-64-02/-128-02

Parameter		Cumbal	S11866-64-02			S11866-128-02			Unit
Paramete	ží	Symbol	Min.	Тур.	Max.	Min.	Тур.	Max.	UIIIL
Spectral response range		λ		200 to 1000			200 to 1000		nm
Peak sensitivity wavelen	gth	λр	-	720	-	-	720	-	nm
Dark output voltage*7	High gain	Vd	-	0.01	0.2	-	0.01	0.2	mV
Dark output voitage	Low gain	vu	-	0.005	0.1	-	0.005	0.1	IIIV
Saturation output voltag	e	Vsat	3	3.5	-	3	3.5	-	٧
Saturation exposure*8	High gain	Esat	-	0.2	0.25	-	0.8	1.0	m/c
Saturation exposure °	Low gain	ESat	-	0.4	0.5	-	1.6	2.0	mlx · s
Dhotoconcitivity	High gain	Sw	14400	18000	-	3520	4400	-	Maria
Photosensitivity	Low gain] SW	7200	9000	-	1760	2200	-	V/ <i>lx</i> · s
Photoresponse nonuniformity*9		PRNU	-	-	±10	-	-	±10	%
Noise*10	High gain	N	-	2.0	3.0	-	1.3	2.0	ma\/ wma.c
	Low gain	N	-	1.1	1.7	-	0.7	1.1	mV rms
Output offset voltage*11		Voffset	-	Vref	-	-	Vref	-	V

^{*7:} Integration time Ts=1 ms

^{*8:} Measured with a 2856 K tungsten lamp.

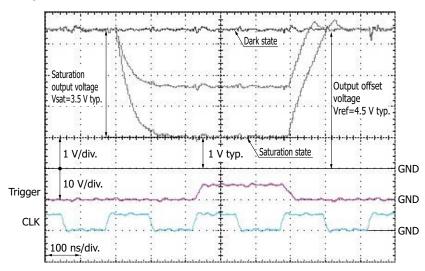
^{*9:} Photoresponse nonuniformity (PRNU) is the output nonuniformity that occurs when the photosensitive area is uniformly illuminated by light which is approx. 50% of the saturation level. PRNU is defined as follows: PRNU = $\Delta X/X \times 100$ [%]

X: average output of all elements, ΔX: difference between X and the maximum or minimum output, whichever is larger.

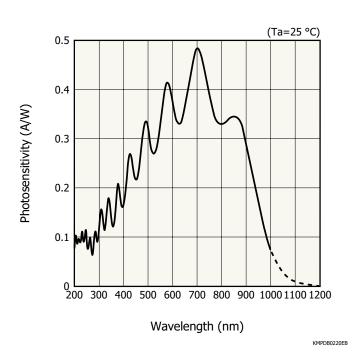
^{*10:} Measured with a video data rate of 50 kHz and Ts=1 ms in dark state.

^{*11:} Video output is negative-going output with respect to the output offset voltage.

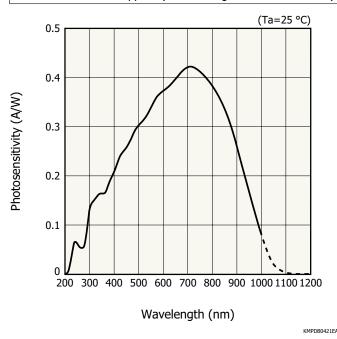
Output waveform of one element



Spectral response (typical example)

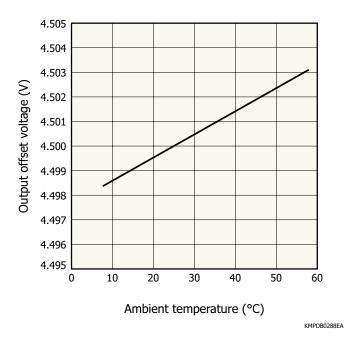


When silicone resin is applied (for attaching a fluorescent screen)

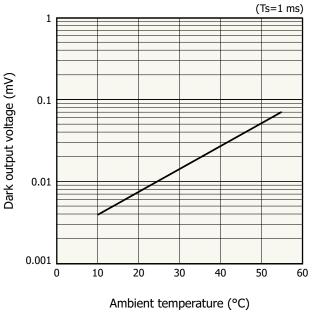


When the fluorescent screen is attached, the spectral response becomes smooth due to the effects of the adhesive resin.

Output offset voltage vs. ambient temperature (measurement example)



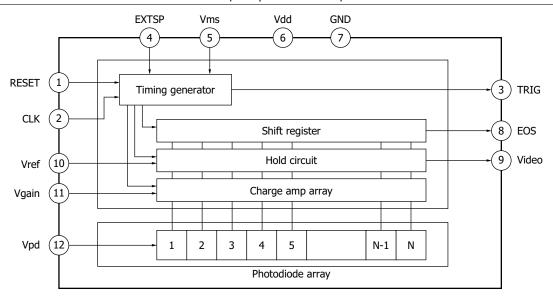
Dark output voltage vs. ambient temperature (typical example)



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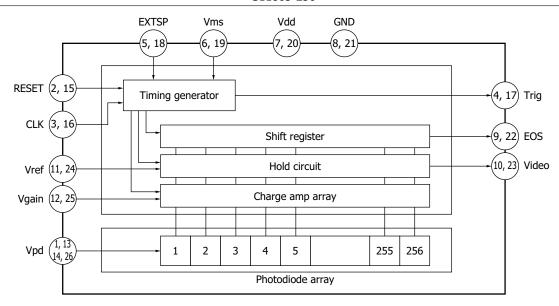
Block diagram

S11865-64/-128, S11866-64-02/-128-02



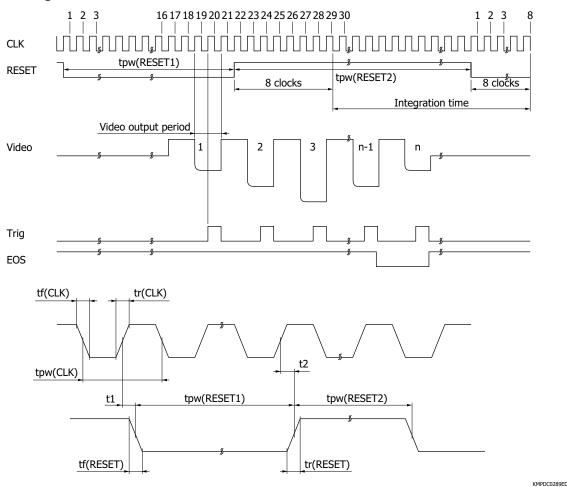
KMPDC0153EA

S11865-256



KMPDC0506EA

- Timing chart

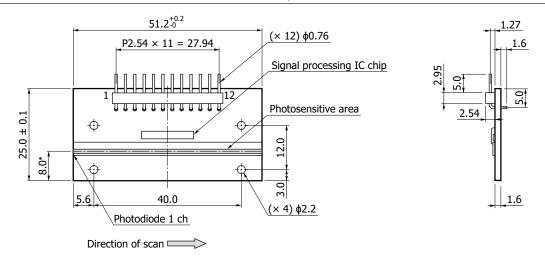


Parameter	Symbol	Min.	Тур.	Max.	Unit
Clock pulse width	tpw(CLK)	250	-	25000	ns
Clock pulse rise/fall times	tr(CLK), tf(CLK)	0	20	30	ns
Reset pulse width 1	tpw(RESET1)	21	-	-	CLK
Reset pulse width 2	tpw(RESET2)	20	-	-	CLK
Reset pulse rise/fall times	tr(RESET), tf(RESET)	0	20	30	ns
Clock pulse-reset pulse timing 1	t1	-20	0	20	ns
Clock pulse-reset pulse timing 2	t2	-20	0	20	ns

- The internal timing circuit starts operation at the falling edge of CLK immediately after a RESET pulse goes Low.
- 2. When the falling edge of each CLK is counted as "1 clock", the video signal of the 1st channel appears between "18.5 clocks and 20.5 clocks". Subsequent video signals appear every 4 clocks.
- 3. The trigger pulse for the 1st channel rises at a timing of 19.5 clocks and then rises every 4 clocks. The rising edge of each trigger pulse is the recommended timing for data acquisition.
- 4. Signal charge integration time equals the High period of a RESET pulse. However, the charge integration does not start at the rise of a RESET pulse but starts at the fall of the 8th clock after the rise of the RESET pulse and ends at the fall of the 8th clock after the fall of the RESET pulse.
 - After the RESET pulse next changes from High to Low, signals integrated within this period are sequentially read out as time-series signals by the shift register operation. The rise and fall of a RESET pulse must be synchronized with the rise of a CLK pulse, but the rise of a RESET pulse must be set outside the video output period. One cycle of RESET pulses cannot be set shorter than the time equal to " $16.5 + 4 \times N$ (number of elements)" clocks.
- 5. The video signal after an EOS signal output becomes a high impedance state, and the video output will be indefinite.

Dimensional outlines (unit: mm)

S11865-64/-128



Tolerance unless otherwise noted: ±0.2

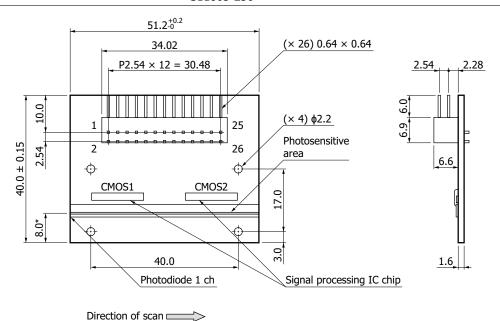
* Distance from board bottom to photosensitive area center

Board: G10 glass epoxy

Connector: PRECI-DIP DURTAL 800-10-012-20-001101

KMPDA0164EG

S11865-256



Tolerance unless otherwise noted: ±0.2

* Length from board bottom to photosensitive area center

Board: G10 glass epoxy

Connector: JAE (Japan Aviation Electronics Industry, Limited) PS-26PE-D4LT1-PN1

KMPDA0191EE



S11866-64-02/-128-02 102.4 +0.3 1.27 P2.54 × 11 = 27.94 1.6 $(\times 12) \phi 0.76$ Signal processing IC chip 2.54 25.0 ± 0.1 Φ Ф 12.0 * 80.0 11.2 Photodiode 1 ch Photosensitive area (4 ×) ¢2.2 Direction of scan

Type no. A S11866-64-02 8.2 S11866-128-02 8.0 Tolerance unless otherwise noted: ±0.2

* Distance from board bottom to photosensitive area center Board: G10 glass epoxy

Connector: PRECI-DIP DURTAL 800-10-012-20-001101

KMPDA0291EB

⇒ Pin connections

S11865-64/-128, S11866-64-02/-128-02

Pin no.	Symbol	Name	Note	
1	RESET	Reset pulse	Pulse input	
2	CLK	Clock pulse	Pulse input	
3	Trig	Trigger pulse	Positive-going pulse output	
4	EXTSP	External start pulse	Pulse input	
5	Vms	Master/slave selection supply voltage	Voltage input	
6	Vdd	Supply voltage	Voltage input	
7	GND	Ground		
8	EOS	End of scan	Negative-going pulse output	
9	Video	Video output	Negative-going output with respect to Vref	
10	Vref	Reference voltage	Voltage input	
11	Vgain	Gain selection terminal voltage	Voltage input	
12	Vpd	Photodiode voltage	Voltage input	

S11865-256

Pin no.	CMOS1	Pin no.	CMOS2	Name	Note
1	Vpd	14	Vpd	Photodiode voltage	Voltage input
2	RESET	15	RESET	Reset pulse	Pulse input
3	CLK	16	CLK	Clock pulse	Pulse input
4	Trig	17	Trig	Trigger pulse	Positive-going pulse output
5	EXTSP	18	EXTSP	External start pulse	Pulse input
6	Vms	19	Vms	Master/slave selection voltage	Voltage input
7	Vdd	20	Vdd	Supply voltage	Voltage input
8	GND	21	GND	Ground	
9	EOS	22	EOS	End of scan	Negative-going pulse output
10	Video	23	Video	Video output	Negative-going output from Vref
11	Vref	24	Vref	Reference voltage	Voltage input
12	Vgain	25	Vgain	Gain selection voltage	Voltage input
13	Vpd	26	Vpd	Photodiode voltage	Voltage input



Gain selection terminal voltage setting

Vdd: High gain (Cf=0.5 pF) GND: Low gain (Cf=1 pF)

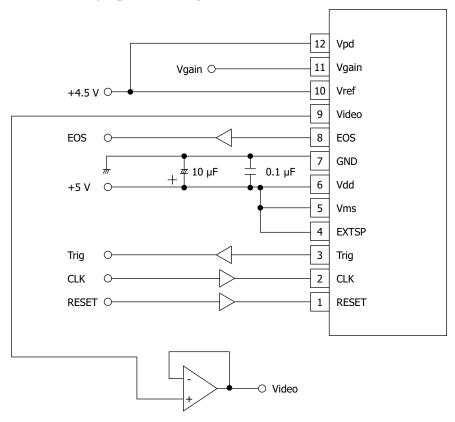
Setting for each readout method

S11865-64/-128, S11866-64-02/-128-02

Set to A in the table below in most cases.

To serially read out signals from two or more sensors linearly connected, set the 1st sensor to A and the 2nd or later sensors to B. The CLK and RESET pulses should be shared with each sensor and the video output terminal of each sensor connected together.

■ Connection example (parallel readout)



High impedance amplifier

KMPDC0288EB

Setting	Readout method	Vms	EXTSP
Α	All stages of parallel readout, serial readout at 1st sensor	Vdd	Vdd
В	Serial readout at 2nd and later sensors	GND	Preceding sensor EOS should be input

S11865-256

Signals of channels 1 through 126 are output from CMOS1, while signals of channels 129 through 256 are output from CMOS2. The following two readout methods are available.

(1) Serial readout method

CMOS1 and CMOS2 are connected in serial and the signals of channels 1 through 256 are sequentially read out from one output line. Set CMOS1 as in "A" in the table below, and set CMOS2 as in "B". CMOS1 and CMOS2 should be connected to the same CLK and RESET lines, and their video output terminals to one line.

(2) Parallel readout method

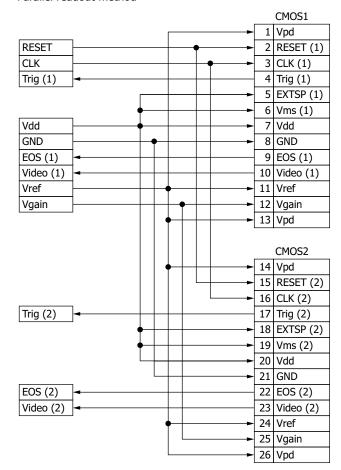
128 channel signals are output in parallel respectively from the output lines of CMOS1 and CMOS2. Set both CMOS1 and CMOS2 as in "A" in the table below.

■ Connection examples

· Serial readout method

CMOS1 Vpd RESET 2 RESET (1) CLK 3 CLK (1) Trig (1) 4 5 EXTSP (1) 6 Vms (1) Vdd 7 Vdd GND 8 GND 9 EOS (1) 10 Video (1) Vref Vref 11 Vgain 12 Vgain 13 Vpd CMOS2 14 Vpd Trig 15 RESET (2) 16 CLK (2) OR Logic IC 17 Trig (2) 74HC32 18 EXTSP (2) 19 Vms (2) 20 Vdd 21 GND EOS 22 EOS (2) Video 23 Video (2) 24 Vref 25 Vgain 26 Vpd KMPDC0222EA

· Parallel readout method



KMPDC0223EB

Setting	Vms	EXTSP
Α	Vdd	Vdd
В	GND	Preceding sensor EOS should be input

- Readout circuit

Check that pulse signals meet the required pulse conditions before supplying them to the input terminals. Video output should be amplified by an operational amplifier that is connected close to the sensor.

Precautions for use

- (1) The signal processing IC chip is protected against static electricity. However, in order to prevent possible damage to the IC chip, take electrostatic countermeasures such as grounding yourself, as well as workbench and tools. Also protect the IC chip from surge voltages from peripheral equipment.
- (2) Gold wires for wire bonding are very thin, so they easily break if subjected to mechanical stress. The signal processing IC chip and wire bonding section are covered with resin for protection. However, never touch these portions. Excessive force, if applied, may break the wires or cause malfunction.
 - Blow air to remove dust or debris if it gets on the protective resin. Never wash them with solvent.
 - Signals may not be obtained if dust or debris is left or a scratch is made on the protective resin, or the signal processing IC chip or photodiode array chip is nicked.
- (3) The photodiode array characteristics may deteriorate when operated at high humidity, so put it in a hermetically sealed enclosure or case. When installing the photodiode array on a board, be careful not to cause the board to warp.

Related information

www.hamamatsu.com/sp/ssd/doc_en.html

- Precautions
- · Disclaimer
- · Unsealed products
- · Image sensors



Driver circuit C9118-01 (sold separately)

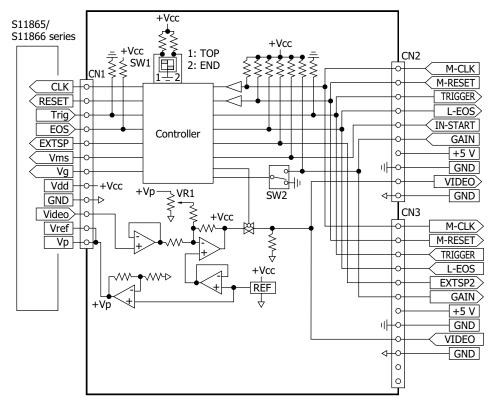
The CMOS driver circuit is designed for S11865/S11866 series photodiode arrays with amplifier. The C9118-01 operates a photodiode by just inputting two signals (M-CLK and M-RESET) and a signal +5 V supply.

Features

- Single power supply (+5 V) operation
- Operation with two input signals (M-CLK and M-RESET)
- **→** Compact: 46 × 56 × 5.2 ^t mm

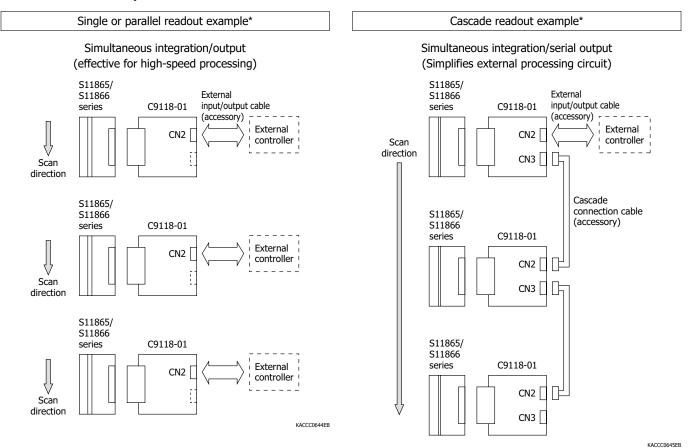


Block diagram



KACCC0643EB

Connection examples



* Switch setting is required.

Information described in this material is current as of May 2022.

Product specifications are subject to change without prior notice due to improvements or other reasons. This document has been carefully prepared and the information contained is believed to be accurate. In rare cases, however, there may be inaccuracies such as text errors. Before using these products, always contact us for the delivery specification sheet to check the latest specifications.

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